

Abstract

(same as the International Publication abstract)

A conventional inspection probe has posed such problems that, when a pitch is as fine as up to 40 μ m, a positional accuracy is difficult to ensure depending on constituting materials and a production method, pin breaking occurs when fine-diameter pins contact, a good contact cannot be obtained due to an insufficient contact, and durability is insufficient. An inspection probe having a probe structure comprising an elastic probe pin, a wiring layer carrying substrate, a backup plate to install a substrate thereon, an inspection substrate and a flexible substrate, characterized in that a good-contact material layer according to the electrode material of a semiconductor device is formed at the tip end of a probe pin and a wiring layer has a structure formed of a low-resistance metal layer, with the good-contact material layer being separated from the low-resistance metal layer. Such a structure can provide very high contact reliability and mechanical durability at a pitch as very fine as up to 40 μ m.